

PATENT APPLICATION TRANSMITTAL LETTER
(Large Entity)

Docket No.
65.0338DIV

TO THE COMMISSIONER FOR PATENTS

Transmitted herewith for filing under 35 U.S.C. 111 and 37 C.F.R. 1.53 is the patent application of:

Chun-Cheng Tsao and John Valliant

For: **METHOD AND APPARATUS FOR GLOBAL DIE THINNING AND POLISHING OF FLIP-CHIP PACKAGED INTEGRATED CIRCUITS**

Enclosed are:

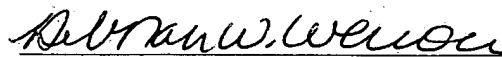
- ☒ Certificate of Mailing with Express Mail Mailing Label No. ER 496109970 US
☒ Six (6) sheets of drawings.
☐ A certified copy of a application.
☒ Declaration ☒ Signed ☐ Unsigned.
☒ Power of Attorney
☐ Information Disclosure Statement
☐ Preliminary Amendment
☒ Other: Copy of orig. Declaration; copy of letter from Petitions Office granting 1.47(a) status; cover letter

CLAIMS AS FILED

For	#Filed	#Allowed	#Extra	Rate	Fee
Total Claims	29	- 20 =	9	x \$18.00	\$162.00
Indep. Claims	5	- 3 =	2	x \$86.00	\$172.00
Multiple Dependent Claims (check if applicable) <input type="checkbox"/>					\$0.00
BASIC FEE					\$770.00
TOTAL FILING FEE					\$1,104.00

- ☐ A check in the amount of to cover the filing fee is enclosed.
☒ The Director is hereby authorized to charge and credit Deposit Account No. 19-0603 as described below.
☒ Charge the amount of \$1,104.00 as filing fee.
☒ Credit any overpayment.
☒ Charge any additional filing fees required under 37 C.F.R. 1.16 and 1.17.
☐ Charge the issue fee set in 37 C.F.R. 1.18 at the mailing of the Notice of Allowance, pursuant to 37 C.F.R. 1.311(b).

Dated: Oct. 23, 2003


Signature

Deborah Wenocur, Reg. No. 40,221
Agent for Applicant
Legal Department, NPTest, LLC
c/o Lasagne Edwards
150 Baytech Drive
San Jose, CA 95134-2302

CC:

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of:

Applicant:	Chung-Chen Tsao and John Valliant) Grp Art Unit: n/a
)
Assignee:	NPTest, LLC) Ex: n/a
)
Serial Number:	unknown)
)
Filed:	n/a)
)
For:	METHOD AND APPARATUS FOR)
	GLOBAL DIE THINNING AND)
	POLISHING OF FLIP-CHIP)
	PACKAGED INTEGRATED)
	CIRCUITS)
)

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

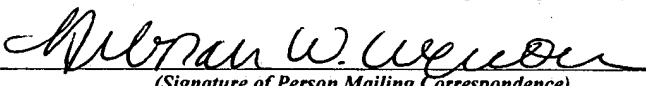
Dear Sir,

The enclosed divisional patent application is being submitted with a new Declaration/POA, signed by the first-named inventor only, so as to explicitly claim priority to the parent application, as well as to name a new agent of record. Also enclosed is a copy of the prior Declaration from the parent application, along with a copy of the letter from the Office of Petitions according to the parent application status under 37 CFR 1.47(a), regarding non-signing inventor John Valliant who could not be located after diligent effort.

Respectfully submitted,

Robert W. Wilson

Deborah W. Wenocur
Reg. No. 40,221
Agent for Applicant
Tel. (650) 493-3849

CERTIFICATE OF MAILING BY "EXPRESS MAIL" (37 CFR 1.10) Applicant(s): Chun-Cheng Tsao and John Valliant			Docket No. 65.0338DIV
Serial No. n/a	Filing Date n/a	Examiner n/a	Group Art Unit n/a
Invention: METHOD AND APPARATUS FOR GLOBAL DIE THINNING AND POLISHING OF FLIP-CHIP PACKAGED INTEGRATED CIRCUITS			
<p>I hereby certify that the following correspondence:</p> <div style="border: 1px solid black; padding: 10px; min-height: 50px;"><p>Application and fee.</p></div> <p style="text-align: center;"><i>(Identify type of correspondence)</i></p> <p>is being deposited with the United States Postal Service "Express Mail Post Office to Addressee" service under 37 CFR 1.10 in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450 on</p> <p style="text-align: center;"><u>October 24, 2003</u> <i>(Date)</i></p> <div style="text-align: right;"><p><u>Deborah W. Wenocur</u> <i>(Typed or Printed Name of Person Mailing Correspondence)</i></p><p> <i>(Signature of Person Mailing Correspondence)</i></p><p><u>ER 496109970 US</u> <i>("Express Mail" Mailing Label Number)</i></p></div>			
<p>Note: Each paper must have its own certificate of mailing.</p>			